

Title (en)

PLASTICIZER-ASSISTED BOND FORMATION USEFUL FOR DEFECT-FREE LAMINATION

Title (de)

MITTELS WEICHMACHER UNTERSTÜTZTE VERBINDUNG FÜR DEFEKTFREIE LAMINIERUNG

Title (fr)

FORMATION DE LIAISON A L'AIDE DE PLASTIFIANT, UTILE POUR STRATIFIES EXEMPTS DE DEF AUT

Publication

EP 1163112 A1 20011219 (EN)

Application

EP 99914949 A 19990319

Priority

US 9906016 W 19990319

Abstract (en)

[origin: WO0056543A1] Laminated articles of the present invention are prepared using at least substrate to be bonded, a polymeric film, and a non-volatile plasticizer for coating at least one surface of the substrate or polymeric film to be bonded. Upon absorption of the plasticizer into the polymeric film, a laminate article is formed. Preferred laminates are useful in optical applications and do not require elevated temperatures and non-atmospheric pressures for timely bonding. Kits comprising an amorphous polymeric film and a sufficient amount of a non-volatile plasticizer for forming a laminate comprising the amorphous polymeric film and a substrate are also useful for practicing the method of the invention.

IPC 1-7

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IPC 8 full level

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